



Material Content Data Sheet



Sales Product Name	BTT6200-4EMA			Issued		4. February 2020		
MA#	MA005347832							
Package	PG-SSOP-24-14			Weight*		151.80 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.840	1.87	1.87	18708	18708
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.068	0.04		446	
	non noble metal	iron	7439-89-6	1.355	0.89		8923	
	non noble metal	copper	7440-50-8	54.998	36.23	37.17	362312	371793
wire	non noble metal	copper	7440-50-8	0.604	0.40	0.40	3977	3977
encapsulation	organic material	carbon black	1333-86-4	0.173	0.11		1142	
	plastics	epoxy resin	-	7.976	5.25		52546	
	inorganic material	silicondioxide	60676-86-0	78.551	51.76	57.12	517467	571155
leadfinish	non noble metal	tin	7440-31-5	2.911	1.92	1.92	19176	19176
plating	noble metal	silver	7440-22-4	1.379	0.91	0.91	9086	9086
glue	plastics	epoxy resin	-	0.162	0.11		1068	
	noble metal	silver	7440-22-4	0.765	0.50	0.61	5037	6105
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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